



REPLACEMENT SHEET

TABLE 2

Comparative Example											
	1	2	3	4	5	6	7	8	9	10	11
Phenol biphenylaralkyl type epoxy resin	7.4	9.4		7.4	7.5	7.6	7.35	7.35	7.4	7.35	7.35
Biphenyl type epoxy resin											
Cresol novolac type epoxy resin			6.9								
Phenol biphenylaralkyl resin	5.5			5.5	5.52	5.65	5.5	5.5	5.5	5.5	5.5
Phenol aralkyl resin			6.0								
Phenol novolac resin		3.5									
Spherical fused silica	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
γ-Glycidylpropyltrimethoxysilane	0.4	0.4	0.4		0.4		0.4	0.4	0.4	0.4	0.4
7-Me rcapto pro pyltrimethoxysilane				0.4							
Triphenylphosphine	0.2	0.15	0.15	0.2	0.08	0.2	0.2	0.2			
DBU									0.2		
Curing accelerator of formula C7)										0.25	
Curing accelerator of formula C8)											0.25
2,3-Dihydroxynaphthalene		0.05	0.05			0.05					
1,2-Dihydroxynaphthalene											
Catechol											
Pyrogallol											
1,6-Dihydroxynaphthalene							0.05				
Resorcinol								0.05			
Carnuba wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)	80	76	71	62	114	76	78	81	68	89	77
Curing torque ratio (%)	65	67	70	62	7	56	65	64	57	85	89
Solder resistance-cracking	4	2	chip	3		9	5	4	4	2	3
Internal crack	0	10	exposure	0	Poor Releasing	0	0	0	0	0	0
Fire retardancy	V-0	V-1	HB	V-0		V-0	V-0	V-0	V-0	V-0	V-0